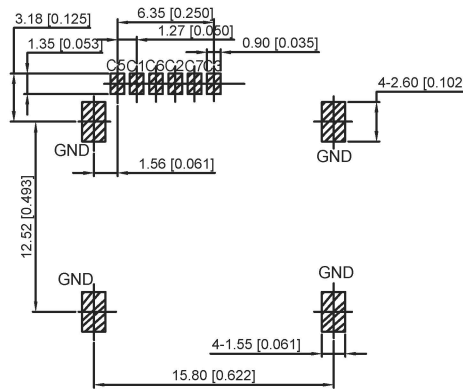


MICRO SIM CARD

■ CIRCUIT TRACE KEEP OUT AREA
 ■ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

NOTES:

MATERIAL:
 Insulator: High Temperature Thermoplastic,
 Contact: Copper Alloy
 Shell: STAINLESS
 PLATING:
 Contact: Plated 30u" Ni Overall, Solder Area: Tin, Contact G/F
 Shell: Plated 30u" Ni Overall
 Plated G/F Selective Contact Area
 Electrical:
 Current Rating :0.5mA max.
 Voltage Rating :50V DC MAX
 Ambient Temperature Range :-20°C~+85°C
 Storage Temperature Range :-40°C~+70°C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100m max.
 Insulation Resistance:1000M min./250V DC
 Dielectric Withstanding Voltage:500V AC
 Mating Cycles:5,000 Insertions
 Temperature: 260°C ±5°

ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	6	COPPER ALLOY	
①	Housing	1	HI-TEMP.PLASIC UL 94V-0	BLACK

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生效日期

MARK	DESCRIPTION	DATE	REVISED	APPROVED	REVISIONS

文件工程章

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DSND	DATE	SCALE: N/A	MODEL TYPE:
DWN	DATE	VIEW:	SIM CARD CONN
CHKD	DATE	UNIT: mm/in	PART NO.:
APPD	DATE	SIZE: A4	DWG NO.:
			XKSIM-002-P6
XKB INDUSTRIAL PRECISION CO., LIMITED			WEIGHT SHEET REVISION
			1.0g 1/1 A0

ANGLAR	±5°
L ≤ 4	±0.2
4 < L ≤ 16	±0.3
16 < L ≤ 63	±0.4
L > 63	±0.5

UNSPECIFIED TOLERANCES